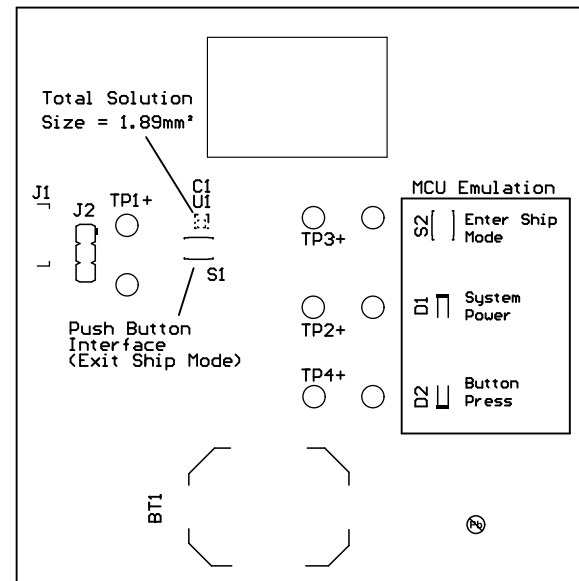


Top Overlay

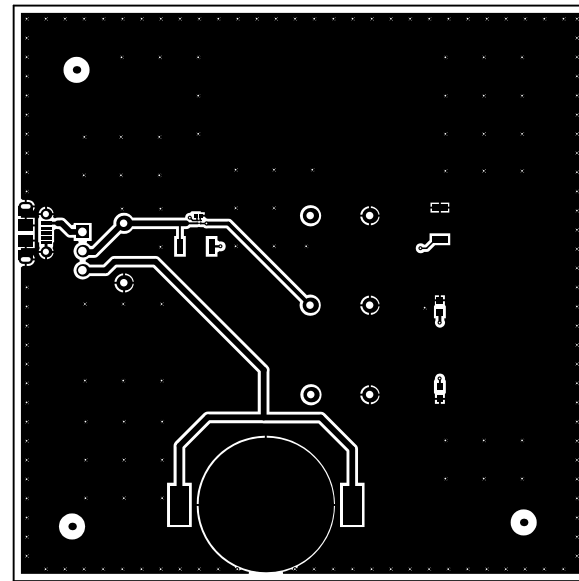


SH-J2

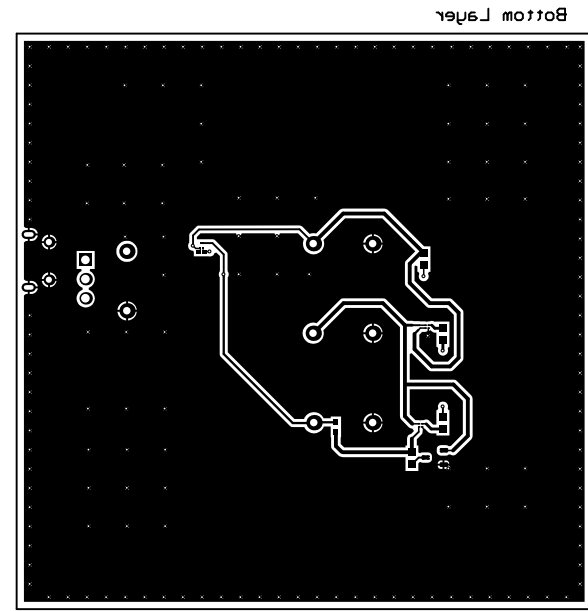
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00556	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 00556		
PLOT NAME = Top Overlay	GENERATED : 11/10/2015 1:31:50 PM	TEXAS INSTRUMENTS	



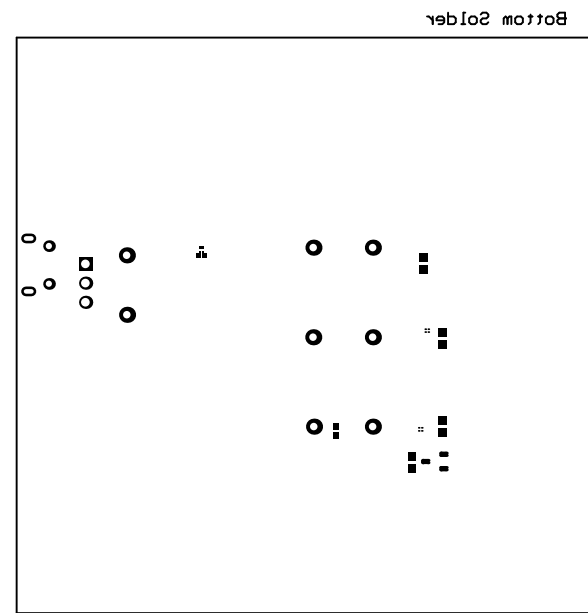
Top Layer



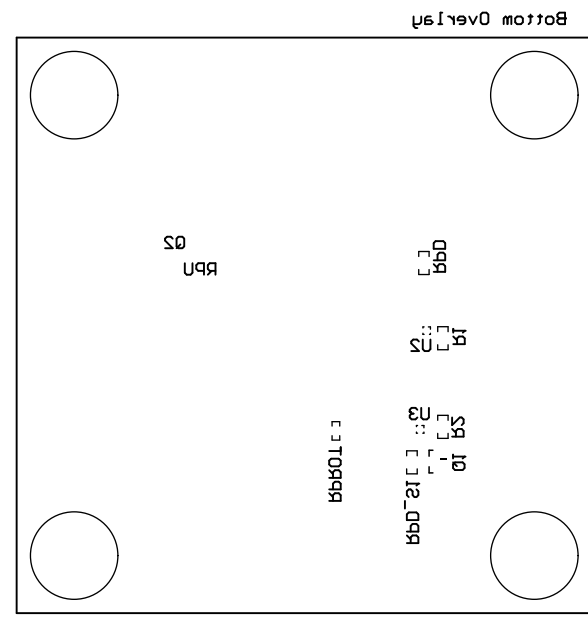
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00556	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 00556		
PLOT NAME = Top Layer	GENERATED : 11/10/2015 1:31:51 PM	TEXAS INSTRUMENTS	



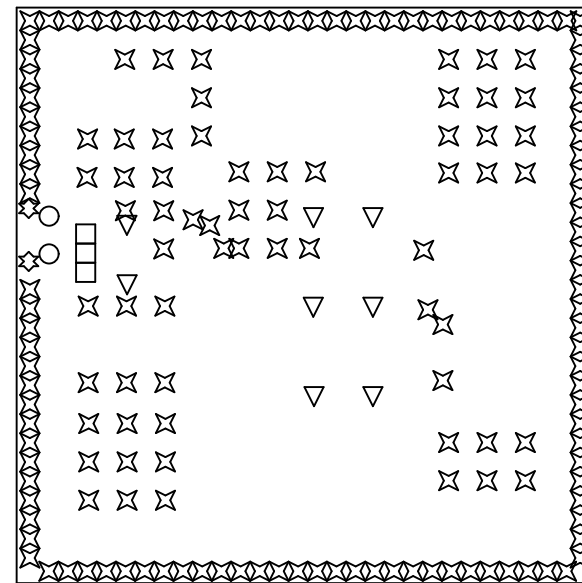
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00556	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 00556		
PLOT NAME = Bottom Layer	GENERATED : 11/10/2015 1:31:52 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00556	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 00556		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/10/2015 1:31:53 PM	TEXAS INSTRUMENTS	

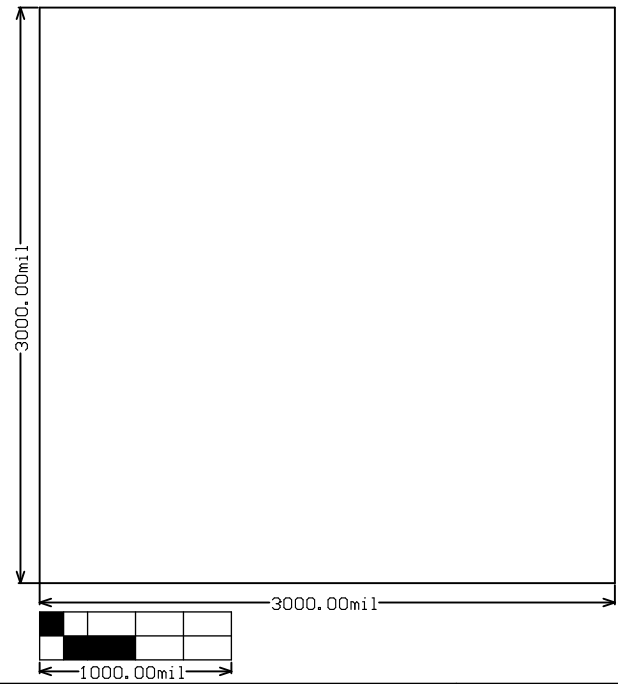


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00556	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 00556		
PLOT NAME = Bottom Overlay	GENERATED : 11/10/2015 1:31:53 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
✕	172	10.00mil (0.254mm)	PTH	Round
○	2	33.46mil (0.850mm)	PTH	Round
▽	8	40.00mil (1.016mm)	PTH	Round
□	3	45.28mil (1.150mm)	PTH	Round
☆	2	23.62mil (0.600mm)	PTH	Slot
	187 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00556	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 00556		
PLOT NAME = Drill Drawing	GENERATED : 11/10/2015 1:31:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00556	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 00556		
PLOT NAME = Board Dimensions	GENERATED : 11/10/2015 1:31:55 PM	TEXAS INSTRUMENTS	



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